

IRS2153(1)D(S)PbF

SELF-OSCILLATING HALF-BRIDGE DRIVER IC

Features

- Integrated 600 V half-bridge gate driver
- C_T, R_T programmable oscillator
- 15.4 V Zener clamp on V_{CC}
- Micropower startup
- Non-latched shutdown on C_T pin (1/6th V_{CC})
- Internal bootstrap FET
- Excellent latch immunity on all inputs and outputs
- +/- 50 V/ns dV/dt immunity
- ESD protection on all pins
- 8-lead SOIC or PDIP package
- Internal deadtime

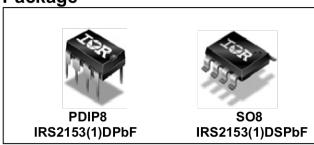
Product Summary

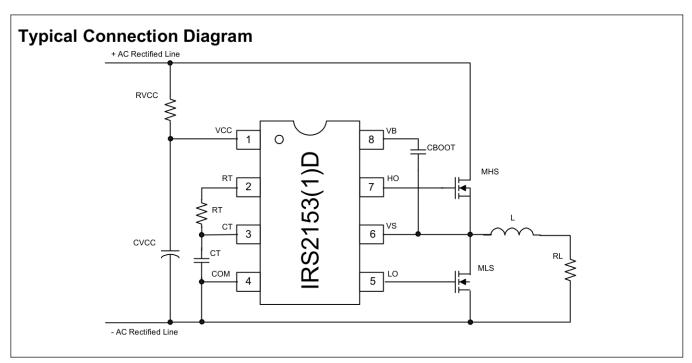
V _{OFFSET}	600 V Max		
Duty cycle	50%		
Driver source/sink current	180 mA/260 mA typ.		
V_{clamp}	15.4 V typ.		
Deadtime	1.1 μs typ. (IRS2153D) 0.6 μs typ. (IRS21531D)		

Description

The IRS2153(1)D is based on the popular IR2153 self-oscillating half-bridge gate driver IC using a more advanced silicon platform, and incorporates a high voltage half-bridge gate driver with a front end oscillator similar to the industry standard CMOS 555 timer. HVIC and latch immune CMOS technologies enable rugged monolithic construction. The output driver features a high pulse current buffer stage designed for minimum driver cross-conduction. Noise immunity is achieved with low di/dt peak of the gate drivers.

Package







Absolute Maximum Ratings

Absolute maximum ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM, all currents are defined positive into any lead. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

	Parameter			
Symbol	Definition	Min.	Max.	Units
V _B	High side floating supply voltage	-0.3	625	
Vs	High side floating supply offset voltage	V _B - 25	V _B + 0.3	V
V _{HO}	High side floating output voltage	V _S – 0.3	V _B + 0.3]
V _{LO}	Low side output voltage	-0.3	V _{CC} + 0.3]
I _{RT}	R _T pin current	-5	5	mA
V _{RT}	R _T pin voltage	-0.3	V _{CC} + 0.3	
V _{CT}	C _T pin voltage	-0.3	V _{CC} + 0.3	V
Icc	Supply current (Note 1)		20	
I _{OMAX}	Maximum allowable current at LO and HO due to external power transistor Miller effect.	-500	500	mA
dV _S /dt	Allowable offset voltage slew rate	-50	50	V/ns
PD	Maximum power dissipation @ T _A ≤ +25 °C, 8-Pin DIP		1.0	
PD	Maximum power dissipation @ T _A ≤ +25 °C, 8-Pin SOIC		0.625	W
R _{thJA}	Thermal resistance, junction to ambient, 8-Pin DIP		85	
R _{thJA}	Thermal resistance, junction to ambient, 8-Pin SOIC		128	°C/W
TJ	Junction temperature	-55	150	
Ts	Storage temperature	-55	150	°C
TL	Lead temperature (soldering, 10 seconds)		300	1

Note 1: This IC contains a zener clamp structure between the chip V_{CC} and COM which has a nominal breakdown voltage of 15.4 V. Please note that this supply pin should not be driven by a DC, low impedance power source greater than the V_{CLAMP} specified in the Electrical Characteristics section.



Recommended Operating Conditions

For proper operation the device should be used within the recommended conditions.

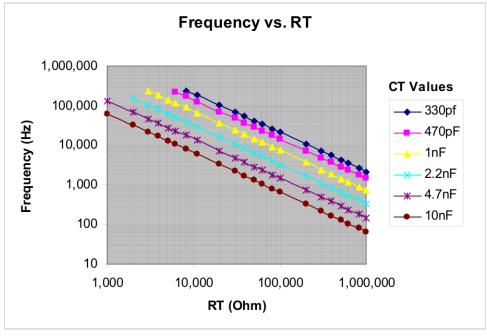
	Parameter			
Symbol	Definition	Min.	Max.	Units
V _{BS}	High side floating supply voltage	V _{CC} - 0.7	V_{CLAMP}	
Vs	Steady state side floating supply offset voltage	-3.0 (Note 2)	600	V
Vcc	Supply voltage	V _{CCUV} + +0.1 V	V _{CC} CLAMP	
Icc	Supply current	(Note 3)	5	mA
TJ	Junction temperature	-40	125	°C

- Note 2: It is recommended to avoid output switching conditions where the negative-going spikes at the V_S node would decrease V_S below ground by more than -5 V.
- **Note 3:** Enough current should be supplied to the V_{CC} pin of the IC to keep the internal 15.6 V zener diode clamping the voltage at this pin.

Recommended Component Values

	Parameter			
Symbol	Component	Min.	Max.	Units
R _T	Timing resistor value	1		kΩ
Ст	C _T pin capacitor value	330		pF

 V_{BIAS} (V_{CC} , V_{BS}) = 14 V, V_{S} =0 V and T_{A} = 25 °C, CLO = CHO = 1 nF.



For further information, see Fig. 12.



Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{BS}) = 14 V, C_{T} = 1 nF, V_{S} =0 V and T_{A} = 25 °C unless otherwise specified. The output voltage and current (V_{O} and I_{O}) parameters are referenced to COM and are applicable to the respective output leads: HO or LO. CLO = CHO = 1 nF.

Symbol	Definition	Min	Тур	Max	Units	Test Conditions
Low Volt	age Supply Characteristics					
V _{CCUV} +	Rising V _{CC} undervoltage lockout threshold	10.0	11.0	12.0		
V _{CCUV} -	Falling V _{CC} undervoltage lockout threshold	8.0	9.0	10.0] v	
V _{CCUVHYS}	V _{CC} undervoltage lockout hysteresis	1.6	2.0	2.4]	
Iqccuv	Micropower startup V _{CC} supply current		130	170		Vcc ≤ Vccuv-
lacc	Quiescent V _{CC} supply current		800	1000	μA	
Icc	V _{CC} supply current		1.8		mA	$R_T = 36.9 \text{ k}\Omega$
V _{CC} CLAMP	V _{CC} zener clamp voltage	14.4	15.4	16.8	V	I _{CC} = 5 mA
Floating	Supply Characteristics					
I _{QBS}	Quiescent V _{BS} supply current		60	80	μA	
V _{BSUV+}	V _{BS} supply undervoltage positive going threshold	8.0	9.0	9.5	V	
V _{BSUV} -	V _{BS} supply undervoltage negative going threshold	7.0	8.0	9.0]	
I _{LK}	Offset supply leakage current	Ī		50	μА	V _B = V _S = 600 V
Oscillato	r I/O Characteristics					
f	On sill atom fine successor	18.4	19.0	19.6	kHz	$R_T = 36.5 \text{ k}\Omega$
fosc	Oscillator frequency	88	93	100	, KHZ	$R_T = 7.15 \text{ k}\Omega$
d	R _T pin duty cycle		50		%	f _o < 100 kHz
I _{CT}	C _T pin current		0.02	1.0	μА	
Ictuv	UV-mode C⊤ pin pulldown current	0.20	0.30	0.6	mA	V _{CC} = 7 V
V _{CT+}	Upper C _T ramp voltage threshold		9.32			
$V_{\text{CT-}}$	Lower C _T ramp voltage threshold		4.66		V	
V_{CTSD}	C _T voltage shutdown threshold	2.2	2.3	2.4		
V_{RT} +	High-level R _T output voltage, V _{CC} - V _{RT}		10	50		I _{RT} = -100 μA
v KI+	Thigh-level IX Output Voltage, VCC - VR		100	300		I _{RT} = -1 mA
V _{RT-}	Low-level R⊤ output voltage		10	50]	I _{RT} = 100 μA
v K I -	Low-love IV output voltage		100	300		I _{RT} = 1 mA
V_{RTUV}	UV-mode R _T output voltage		0	100		$V_{CC} \leq V_{CCUV}$
Vozas	SD-mode Re output voltage Ves - Ves		10	50	mV	I _{RT} = -100 μA, V _{CT} = 0 V
V _{RTSD}	SD-mode R _T output voltage, V _{CC} - V _{RT}		100	300		I _{RT} = -1 mA, V _{CT} = 0 V



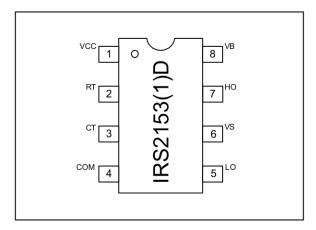
Electrical Characteristics

 V_{BIAS} (V_{CC} , V_{BS}) = 14 V, C_T = 1 nF, V_S =0 V and T_A = 25 °C unless otherwise specified. The output voltage and current (V_o and I_o) parameters are referenced to COM and are applicable to the respective output leads: HO or LO. CLO = CHO = 1 nF.

Symbol	Definition	Min	Тур	Max	Units	Test Conditions	
Gate Driver Output Characteristics							
V _{OH}	High-level output voltage		Vcc			L 0 A	
V _{OL}	Low-level output voltage		СОМ		V	Io = 0 A	
V _{OL_UV}	UV-mode output voltage		СОМ			Io=0 A, Vcc≤Vccuv-	
t _r	Output rise time		120	220			
t _f	Output fall time		50	80	ns		
t _{sd}	Shutdown propagation delay		350				
t _d	Output deadtime (HO or LO) (IRS2153D)	0.65	1.1	1.75	μs		
t _d	Output deadtime (HO or LO) (IRS21531D)	0.35	0.6	0.85	μS		
I _{O+}	Output source current		180		mA		
I _{O-}	Output sink current		260		IIIA		
Bootstra	p FET Characteristics						
V_{B_ON}	V _B when the bootstrap FET is on		13.7		V		
I _{B_CAP}	V _B source current when FET is on	40	55		mA	C _{BS} =0.1 uF	
I _{B_10V}	V _B source current when FET is on	10	12		l IIIA	V _B =10 V	

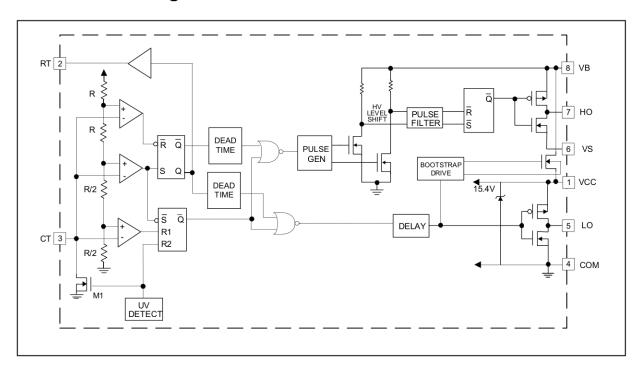


Lead Definitions



	Lead			
Symbol	Description			
Vcc	Logic and internal gate drive supply voltage			
R _T	Oscillator timing resistor input			
Ст	Oscillator timing capacitor input			
COM	IC power and signal ground			
LO	Low-side gate driver output			
Vs	High voltage floating supply return			
НО	High-side gate driver output			
V _B	High side gate driver floating supply			

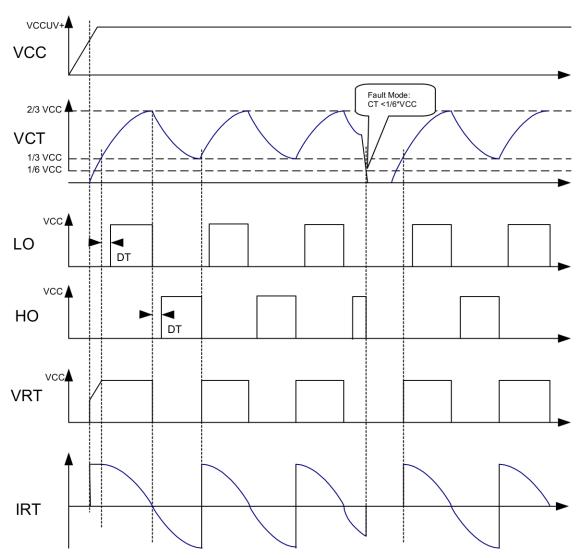
Functional Block Diagram





Timing Diagram

Operating Mode

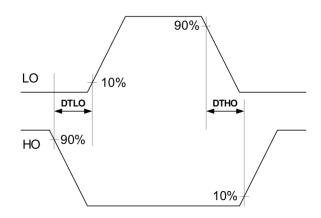


Switching Time Waveform

tf tr 90% НО LO

10%

Deadtime Waveform





Functional Description

Under-voltage Lock-Out Mode (UVLO)

The under-voltage lockout mode (UVLO) is defined as the state the IC is in when V_{CC} is below the turn-on threshold of the IC. The IRS2153(1)D under voltage lock-out is designed to maintain an ultra low supply current of less than 170 μA , and to guarantee the IC is fully functional before the high and low side output drivers are activated. During under voltage lock-out mode, the high and low-side driver outputs HO and LO are both low.

Supply voltage

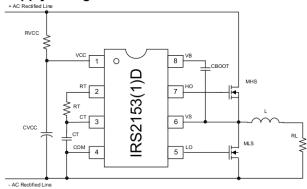


Fig. 1 Typical Connection Diagram

Fig. 1 shows an example of supply voltage. The start-up capacitor (C_{VCC}) is charged by current through supply resistor (R_{VCC}) minus the start-up current drawn by the IC. This resistor is chosen to provide sufficient current to supply the IRS2153(1)D from the DC bus. C_{VCC} should be large enough to hold the voltage at Vcc above the UVLO threshold for one half cycle of the line voltage as it will only be charged at the peak, typically 0.1 uF. It will be necessary for R_{VCC} to dissipate around 1 W.

The use of a two diode charge pump made of DC1, DC2 and CVS (Fig. 2) from the half bridge (V_S) is also possible however the above approach is simplest and the dissipation in R_{VCC} should not be unacceptably high.

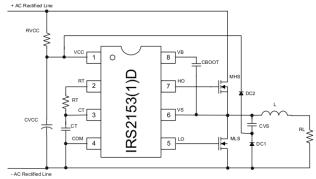


Fig. 2 Charge pump circuit

The supply resistor (R_{VCC}) must be selected such that enough supply current is available over all operating conditions.

Once the capacitor voltage on V_{CC} reaches the start-up threshold $V_{\text{CCUV+}},$ the IC turns on and HO and LO begin to oscillate.

Bootstrap MOSFET

The internal bootstrap FET and supply capacitor (C_{BOOT}) comprise the supply voltage for the high side driver circuitry. The internal boostrap FET only turns on when LO is high. To guarantee that the high-side supply is charged up before the first pulse on pin HO, the first pulse from the output drivers comes from the LO pin.

Normal operating mode

Once the $V_{\text{CCUV+}}$ threshold is passed, the MOSFET M1 opens, RT increases to approximately V_{CC} (V_{CC} - $V_{\text{RT+}}$) and the external CT capacitor starts charging. Once the CT voltage reaches $V_{\text{CT-}}$ (about 1/3 of V_{CC}), established by an internal resistor ladder, LO turns on with a delay equivalent to the deadtime (t_{d}). Once the CT voltage reaches $V_{\text{CT+}}$ (approximately 2/3 of V_{CC}), LO goes low, RT goes down to approximately ground ($V_{\text{RT-}}$), the CT capacitor discharges and the deadtime circuit is activated. At the end of the deadtime, HO goes high. Once the CT voltage reaches $V_{\text{CT-}}$ HO goes low, RT goes high again, the deadtime is activated. At the end of the deadtime, LO goes high and the cycle starts over again.

The following equation provides the oscillator frequency:

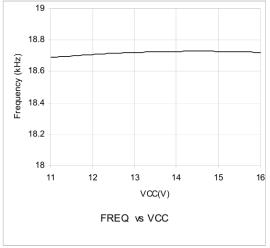
$$f \sim \frac{1}{1.453 \times RT \times CT}$$

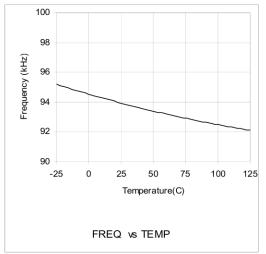
This equation can vary slightly from actual measurements due to internal comparator over- and under-shoot delays. For a more accurate determination of the output frequency, the frequency characteristic curves should be used (RT vs. Frequency, page 3).

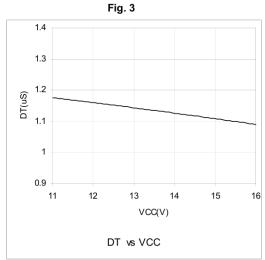
Shut-down

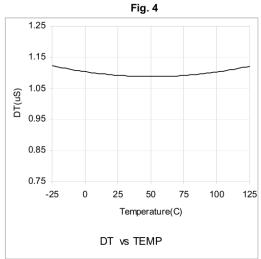
If CT is pulled down below VCTSD (approximately 1/6 of V_{CC}) by an external circuit, CT doesn't charge up and oscillation stops. LO is held low and the bootstrap FET is off. Oscillation will resume once CT is able to charge up again to V_{CT}.

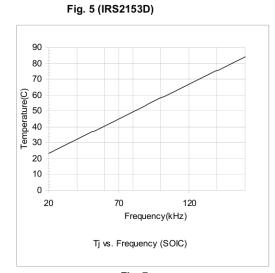
International TOR Rectifier

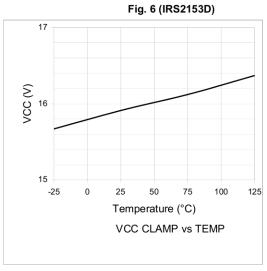




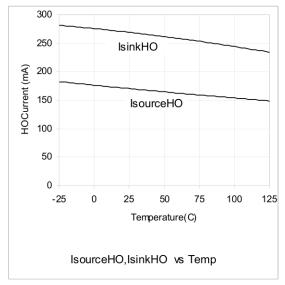








International **TOR** Rectifier



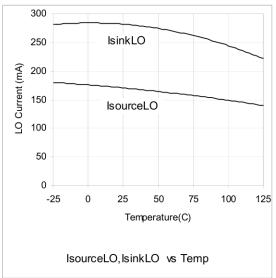


Fig. 10

Fig. 9 80 70 IB_CAP IB_CAP, IBS_10V (mA) 50 40 30 IBS_10V 20 10 0 -25 0 25 50 75 100 125 Temperature(C) IBCAP, IBS10V vs TEMP

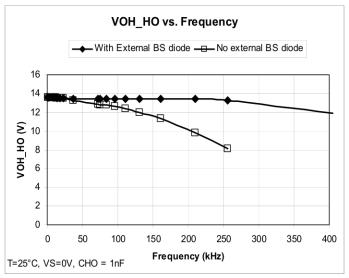


Fig. 11 Fig. 12

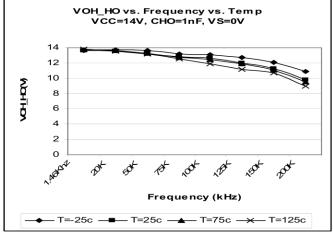
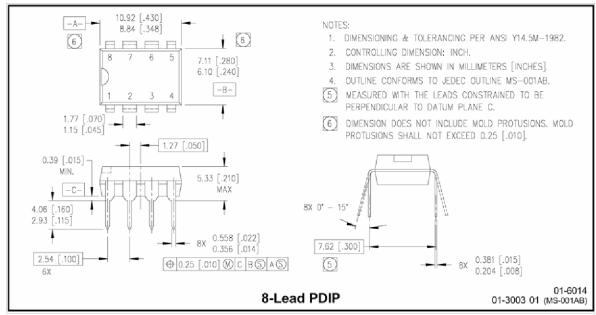
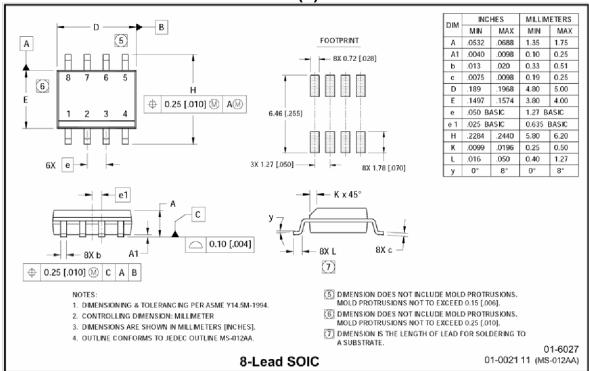


Fig. 13



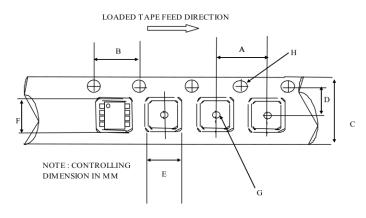


IRS2153(1)DPbF



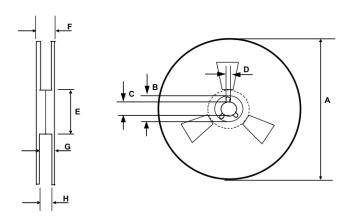
IRS2153(1)DSPbF





CARRIER TAPE DIMENSION FOR 8SOICN

CARRIER TAFE DIMENSION FOR 830101					
	Me	tric	Imperial		
Code	Min	Max	Min	Max	
Α	7.90	8.10	0.311	0.318	
В	3.90	4.10	0.153	0.161	
С	11.70	12.30	0.46	0.484	
D	5.45	5.55	0.214	0.218	
E	6.30	6.50	0.248	0.255	
F	5.10	5.30	0.200	0.208	
G	1.50	n/a	0.059	n/a	
Н	1.50	1.60	0.059	0.062	

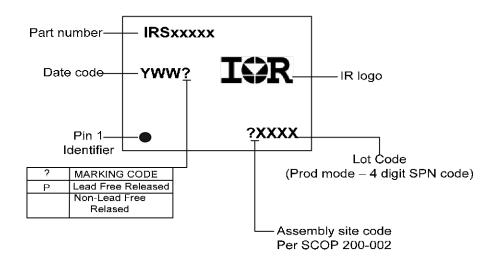


REEL DIMENSIONS FOR 8SOICN

	Metric		Imp	erial	
Code	Min	Max	Min	Max	
Α	329.60	330.25	12.976	13.001	
В	20.95	21.45	0.824	0.844	
B C D E	12.80	13.20	0.503	0.519	
D	1.95	2.45	0.767	0.096	
E	98.00	102.00	3.858	4.015	
	n/a	18.40	n/a	0.724	
G H	14.50	17.10	0.570	0.673	
H	12.40	14.40	0.488	0.566	



PART MARKING INFORMATION



ORDER INFORMATION

8-Lead PDIP IRS2153DPbF 8-Lead PDIP IRS21531DPbF

8-Lead SOIC IRS2153DSPbF

8-Lead SOIC IRS21531DSPbF

8-Lead SOIC Tape & Reel IRS2153DSTRPbF

8-Lead SOIC Tape & Reel IRS21531DSTRPbF



The SOIC-8 is MSL2 qualified.

This product has been designed and qualified for the industrial level.

Qualification standards can be found at www.irf.com http://www.irf.com IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, Tel: (310) 252-7105

Data and specifications subject to change without notice. 6/27/2006